



Material Content Data Sheet



Sales Product Name		IFX25001ME V25		Issued		29. August 2013		
MA#		MA000741328						
Package		PG-SOT223-4-21		Weight*		112.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.163	1.04	1.04	10376	10376
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		90	
	non noble metal	titanium	7440-32-6	0.051	0.05		453	
	non noble metal	chromium	7440-47-3	0.152	0.14		1358	
	non noble metal	copper	7440-50-8	50.489	45.06	45.26	450637	452538
wire	noble metal	gold	7440-57-5	0.117	0.10	0.10	1048	1048
encapsulation	organic material	carbon black	1333-86-4	0.461	0.41		4118	
	plastics	brominated resin	-	0.577	0.51		5148	
	inorganic material	antimonytrioxide	1309-64-4	1.154	1.03		10296	
	plastics	epoxy resin	-	10.497	9.37		93692	
	inorganic material	silicondioxide	60676-86-0	44.988	40.15	51.47	401539	514793
leadfinish	non noble metal	tin	7440-31-5	1.464	1.31	1.31	13067	13067
plating	noble metal	silver	7440-22-4	0.513	0.46	0.46	4579	4579
glue	plastics	epoxy resin	-	0.071	0.06		630	
	noble metal	silver	7440-22-4	0.333	0.30	0.36	2969	3599
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com